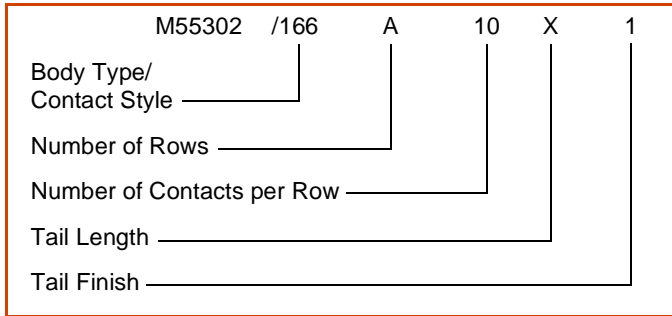


Low Mating Force

how to order (military types)

MB, DB, PC Connectors Military Part Number Ordering Procedure

Example part number M55302/166A10X1 is shown as follows:



Body Type/Contact Style

- /166 designates MB-P (Mother Board, Printed Circuit Board Termination)
- /167 designates MB-W (Mother Board, Wire-wrap Contacts)
- /168 designates PC (Printed Circuit, 90° Printed Circuit Board Termination)
- /170 designates DB (Daughter Board, 90° Printed Circuit Board Termination)

Number of Rows

- A – 2 Rows
- B – 3 Rows
- C – 4 Rows

Number of Contacts per Row

Contact counts per row range from 10 to 100
(Only 2 digits permitted in this space; for 100 contacts per row, use 00)

Tail Length

MB-P (PCB Termination)*	MB-W** (Wire-wrap)
X – .300 ±.025	Y – .700 ±.025
Y – .145 ±.025	Z – .542 ±.025
Z – .113 ±.025	

DB*	PC*
X – .300 ±.025	Y – .150 +.035 –.025
Y – .150 ±.025	Z – .095 +.035 –.025
Z – .120 ±.025	

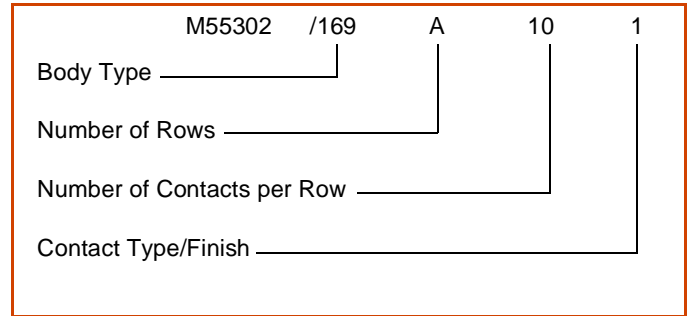
* Reference "J" Dimension on all connector drawings in this catalog.
** For MB-W only: Reference "H" Dimension on connector drawing on page 12.

Tail Finish

- Tin lead per MIL-P-81728, 50 to 70% tin, .0001 min. thick over copper
- Gold per MIL-G-45204, type II, grade C, class 00 (01 for MB-W) over nickel per QQ-N-290

IO Connectors Military Part Number Ordering Procedure

Example part number M55302/169A101 is shown as follows:



Body Type

- /169 designates IO (Input/Output)
(Contact type/finish is last digit of IO part number - see list of options below)

Number of Rows

- A – 2 Rows
- B – 3 Rows
- C – 4 Rows

Number of Contacts per Row

Contact counts per row range from 10 to 100
(Only 2 digits permitted in this space; for 100 contacts per row, use 00)

Contact Type/Finish

- Crimp contact – Tin lead per MIL-P-81728, 50 to 70% tin, .0001 min. thick over copper
- Crimp contact – Gold per MIL-G-45204, type II, grade C, class 1 over copper
- Connectors supplied less contacts
- PCB contacts installed with .145 ±.025 stickout – Tin lead per MIL-P-81728, 50 to 70% tin, .0001 min. thick over copper (Reference "J" Dimension on connector drawing on page 20).

To Order IO Contacts

(For use with connectors less contacts)

M55302/171-1

_____ suffix designates crimp well finish

Crimp well finish

- Crimp contact – Tin lead per MIL-P-81728, 50 to 70% tin, .0001 min. thick over copper
- Crimp contact – Gold per MIL-G-45204, type II, grade C class 1 over copper

To order Accessories, see page 7.

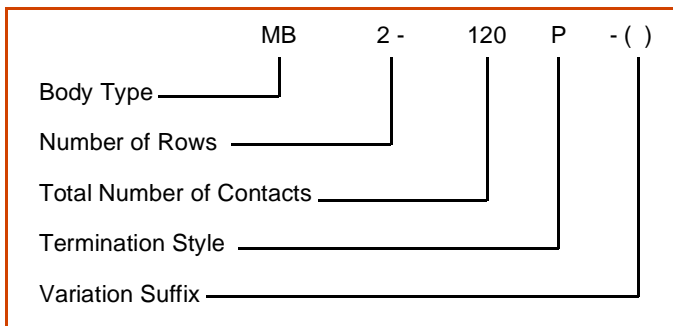
Low Mating Force

how to order (proprietary types)

MB, DB, IO, PC Connectors

Proprietary Part Number Ordering Procedure

Example part number MB2-120P- () is shown as follows:



Body Type

MB designates Mother Board
 DB designates Daughter Board
 IO designates Input/Output
 PC designates Printed Circuit

Number of Rows

2, 3 or 4 rows

Total Number of Contacts

See Contact Arrangements, pages 8 and 9

Standard Termination Style

(Stickout values below apply to "J" dimension referenced on individual connector catalog pages.)

MBX-XXXP	Straight PCB stud, .021 dia, .113 ±.025 stickout, Sn/Ni plate
MBX-XXXW	Solderless wrap, .025 sq., .507 ±.025 stickout, Sn/Ni plate
DBX-XXXP	90° PCB stud, .021 dia, .085 ±.025 stickout, Sn/Ni plate
IOX-XXXX	Crimp, rear removable contact, size 22D wire well, Sn/Ni plate
IOX-XXXP	PCB stud, .021 dia, .145 ±.025 stickout, Sn/Ni plate
PCX-XXXP	90° PCB stud, .021 dia, .095 ^{+ .035} / _{-.025} stickout, Sn/Ni plate

LEGEND:

Sn/Ni designates Tin over Nickel
 Au/Ni designates Gold over Nickel
 Au/Cu designates Gold over Copper
 SnPb/Cu designates Tin-Lead over Copper

Variation Suffix

(Stickout values below apply to "J" dimension referenced on individual connector catalog pages.)

(700)	Gold plate in accordance with MIL-G-45204, type II, .000030 min. thick gold (.000050 for solderless wrap) over .000050 min. thick nickel (standard termination length)
(701)	Gold plate in accordance with MIL-G-45204, type II, .000050 min. thick gold over .00015 min. thick copper (standard termination length)
(702)	PCB stud stickout of .145, Sn/Ni plate, MB-P
(703)	Au/Ni [same as (700)], PCB stud stickout of .145, MB-P
(704)	Au/Cu [same as (701)], PCB stud stickout of .145, MB-P
(705)	90° PCB stud, .120 stickout, Sn/Ni plate, DB
(706)	Au/Ni [same as (700)], 90° PCB stud .120 stickout, DB
(707)	Au/Cu [same as (701)], 90° PCB .120 stickout, DB
(709)	PCB stud stickout of .300 DB (90°), .300 MB-P & .335 IO-P, Sn/Ni plate
(710)	Solderless wrap, .025 sq., .665 stickout, Sn/Ni plate, MB-W
(711)	Solderless wrap, .025 sq., .665 stickout, Au/Ni, [same as (700)], MB-W
(713)	PCB stud stickout of .060, Sn/Ni plate, IO-P
(714)	90° PCB stud stickout of .150, Sn/Ni plate, PC & DB
(715)	Solderless wrap, .025 sq., .665 stickout, Au/Cu [same as (701)], MB-W
(716)	90° PCB stud stickout of .085 matte tin, DB
(717)	90° PCB stud stickout of .095 matte tin, PC
(718)	90° PCB stud stickout of .120 matte tin, DB
(719)	PCB stud stickout of .300 MB-P & .335 IO-P, matte tin
(720)	PCB stud stickout of .060 matte tin, IO-P
(721)	PCB stud stickout of .500, Sn/Ni plate, IO-P
(722)	PCB stud stickout of .356 matte tin, MB-P
(723)	PCB stud stickout of .192, Sn/Ni plate, MB-P
(724)	90° PCB stud stickout of .095, RTV potted rear, Sn/Ni plate, PC
(725)	90° PCB stud stickout of .120, RTV potted rear, Sn/Ni plate, DB
(726)	90° PCB stud stickout of .150, RTV potted rear, Sn/Ni plate, PC & DB
(727)	PCB stud stickout of .145, RTV potted rear, Sn/Ni plate, MB-P
(728)	PCB stud stickout of .145, Au/Ni, [same as (700)], RTV potted rear, MB-P
(729)	90° PCB stud stickout of .120, Au/Ni, [same as (700)], RTV potted rear, DB
(730)	90° PCB stud stickout of .150, Au/Ni, [same as (700) above], PC and DB
(731)	PCB stud stickout of .145, matte tin, MB-P

Variation Suffixes continued on next page.